Method for detaching a semiconductor chip from a foil

ABSTRACT

A method for detaching a semiconductor chip from a foil uses a die ejector comprising plates having a straight supporting edge and an L-shaped supporting edge comprises:

lifting of the plates to a height H_1 above the surface of a cover plate;

lowering of a first pair of plates with L-shaped supporting edge;

optionally, lowering of a second pair of plates with L-shaped supporting edge;

lifting of the plates that have not yet been lowered to a height $H_2 > H_1$;

staggered lowering of plates that have not yet been lowered, with at least one or several plates not being lowered;

optionally, lowering of the plates that have not yet been lowered to a height $H_3 < H_2$;

lowering of the plates until all plates are lowered, and

moving away of the chip gripper,

wherein the chip gripper touches the semiconductor chip before lowering the last three plates.

Figure 8